## TELEDYNE SEMICONDUCTOR

## TSC8750 3 1/2 Digit ADC w/Parallel BCD Output • 10 mS Conversion Time • Latched Outputs

## **General Description**

The Teledyne Semiconductor TSC8750 is a 3 1/2 digit monolithic CMOS analog-to-digital converter. Fully self-contained in a single 24-pin dual in-line package, the converter requires only passive support components, voltage or current reference and power supplies.

Conversion is performed by an incremental charge balancing technique which has inherently high accuracy, linearity and noise immunity. An amplifier integrates the sum of the unknown analog current and pulses of a reference current. The number of pulses (charge increments) needed to maintain the amplifier summing junction near zero are counted. At the end of conversion the total count is latched into the digital outputs in a 3 1/2 digit parallel BCD digital format.

## **Ordering Information**

Part No.	Package	Temperature Range		
TSC8750CJ	24-Pin Plastic Dip	0°C to +70°C		
TSC8750CN	24-Pin Ceramic	-40°C to +85°C		
TSC8750BN	24-Pin Ceramic	-55° C to +125° C		

## **Pin Configuration**



#### Features

- High Accuracy 3 1/2 Digit Resolution With < ±0.025% Error
- Military Temperature Range Devices
- Monotonic Performance No Missing Codes
- Monolithic CMOS Construction Gives Low Power Dissipation — 20 mW Typical
- Contains All Required Active Elements Needs only Passive Support Components, Reference Voltage and Dual Power Supply
- High Stability Over Full Temperature Range
  - Gain Temperature Coefficient Typically <25 ppm/°C Zero Drift Typically <30  $\mu$ V/°C
- Differential Non-Linearity Drift Typically <2.5 ppm/° C
- Latched Parallel BCD Outputs
- LPTTL and CMOS Compatible Outputs and Control Inputs
- Strobed or Free Running Conversion
- Infinite Input Range Any Positive Voltage Can Be Applied Via a Scaling Resistor

## **Absolute Maximum Ratings**

Storage Temperature
Operating Temperature
BN –55° C to + 125° C
CN40° C to + 85° C
CJ 0° to + 70° C
VDD -VSS 18 V
lin ±10 mA
IREF ±10 mA
Digital Input Voltage0.3 to V <sub>DD</sub> +0.3 V
Operating VDD and VSS Range 3.5 V to 7 V
Package Dissipation 500 mW
Lead Temperature 300°C
(Soldering, 10 seconds)

#### HANDLING PRECAUTIONS

CMOS devices must be handled correctly to prevent damage. Package and store only in conductive foam, anti-static tubes or other conductive material. Use proper anti-static handling procedures. Do not connect in circuits under "power on" conditions, as high transients may cause permanent damage.

## **TSC8750**

#### 3 1/2 Digit ADC w/Parallel BCD Output • 10 mS Conversion Time • Latched Outputs

**Electrical Characteristics** Unless otherwise specified,  $V_{DD} = +5 V$ ,  $V_{SS} = -5 V$ ,  $V_{GND} = 0$ ,  $V_{REF} = -6.4 V$ ,  $R_{BIAS} = 100 k\Omega$ , test circuit shown.  $T_A = 25^{\circ}$ C unless Full Temperature Range is specified. (-55°C to +125°C for BN, -40°C to +85°C for CN package, 0° to 70°C for CJ package.)

					CJ/CL BL		
PARAMETER	DEFINITION	CONDITIONS	MIN	ТҮР	MAX	MAX	UNITS
Accuracy	· · · · · · · · · · · · · · · · · · ·						
Resolution Accuracy	BCD Word Length Of Digital Output		3 1/2 (1999 Counts)			-	Digits
Relative Accuracy	Output Deviation From Straight Line Between Normalized Zero and Full-Scale Input				0.025	0.025	%
Differential Non-Linearity	Deviation From 1 LSB Between Transition Points		<u> </u>			0.025	0.025%
Differential Non-Linearity Temperature Drift	Variation in Differential Non-Linearity Due To Temperature Change	Full Temperature Range		±2.5	±5	±5	ppm/° C
Gain Variance	Variation From Exact (Compen- sate By Trimming R <sub>IN</sub> or R <sub>REF</sub> )	n hand die seine andere einen andere einen ei L		±2	±5	±5	% of Nominal
Gain Temperature Drift	Variation In A Due To Temperature Change	Full Temperature Range		±25	±75	±80	ppm/°C
Zero Offset	Correction at Zero Adjust to Give Zero Output When Input Is Zero	I <sub>IN</sub> = 0		±10	±50	±50	mV
Zero Temperature Drift	Variation in Zero Offest Due to Temperature Change	Full Temperature Range		±3	±5	±8	ppm/°C
Analog Inputs							
I <sub>IN</sub> Full-Scale	Full-Scale Analog Input Current To Achieve Specified Accuracy		_	10	_		μA
I <sub>REF</sub> (Note 1)	Reference Current Input To Achieve Specified Accuracy			-20			μA
Digital Inputs							
VIN	Logical "1" Input Threshold For Initiate Conversion Input	Full Temperature Range	3.5		—		۷
V <sub>IN</sub> <sup>(0)</sup>	Logical "0" Input Threshold For Initiate Conversion Input	Full Temperature Range			1.5	1.5	۷
Digital Outputs	· · · ·						
Vout <sup>(1)</sup>	Logical "1" Output Voltage For Digits Out, Busy, and Data Valid Outputs	Full Temp. Range Ι <sub>ΟUT</sub> = -10 μΑ Ι <sub>ΟUT</sub> = -500 μΑ	4.5	-			v
Vout <sup>(0)</sup>	Logical "0" Output Voltage For Digits Out, Busy, and Data Valid Outputs	Full Temp. Range V <sub>DD</sub> = 4.75 V I <sub>OUT</sub> = 500 µA			0.4	0.4	v
Dynamic							
Conversion Time	Time Required to Perform One Complete A/D Conversion	Full Temp. Range	_	10	12	12	ms
Conversion Rate in Free-Run Mode		VINT CONV = + 5 V	84	100	_	-	Conv'ns per Second
Minimum Pulse Width for Initiate Conversion		Full Temp. Range	500		_		ns

#### 3 1/2 Digit ADC w/Parallel BCD Output • 10 mS Conversion Time

#### Latched Outputs

## **TSC8750**

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PARAMETER	DEFINITION	CONDITIONS	MIN	ТҮР	CJ/CL MAX	BL MAX	UNITS
Supply Current IDD Quiescent (N Package) (J Package)	Current Required From Positive Supply During Operation	Full Temp. Range VINT CONV = OV		1.4 1.4	2.5 5.0	3.5	mA mA
Iss Quiescent (N Package) (J Package)	Current Required From Negative Supply During Operation	Full Temp. Range VINIT CONV = OV		-1.6 -1.6	-2.5 -5.0	-3.5	mA mA
Supply Sensitivity	Change in Full-Scale Gain vs Supply Voltage Change	$V_{DD} \pm 1V$ , $V_{SS} \pm 1V$		±0.5	±1.0	±1.0	%/V
$ V_{DD}  =  V_{SS}  = 5 V \pm 1 V$	Change in Full-Scale Gain vs Supp Voltage Change for Tracking Supp	ily lies	±0.05	±0.1	±0.1	±0.1	%/V

NOTE:

IN and IREF pins connect to the summing junction of an operational amplifier. Voltage sources cannot be attached directly but must be buffered by external resistors. See Test Circuit.

## **Test Circuit**



## **Circuit Description**

During conversion the sum of a continuous current  $I_{IN}$  and pulses of a reference current  $I_{REF}$  is integrated for a fixed number of clock periods.  $I_{IN}$  is proportional to the analog input voltage;  $I_{REF}$  is switched in for exactly one clock period just frequently enough to maintain the summing input of the integrator near zero. Thus, the charge from the continuous  $I_{IN}$  current is balanced against the pulses of  $I_{REF}$ current. The total number of  $I_{REF}$  pulses needed during the conversion period to maintain the charge balance is counted, and the result (in BCD) is latched into the outputs at the end of conversion.

The converter contains two counters and a clock in addition to an operational amplifier, comparator, latching output buffers and housekeeping logic. One counter is a clock counter which (after a reset pulse) starts counting clock pulses; when the required count is reached, the clock counter generates a pulse to start the end-of-conversion routine.

## **TSC8750**

The other counter is a data counter, which is reset synchronously with the clock counter and counts the number of times the IREF current is switched into the summing input of the amplifier during the period defined by the clock counter.

When the Initiate Conversion input is strobed with a positive signal, the busy line latches high and a 10  $\mu$ s (times given are approximate) start up cycle begins. The integrating capacitor is discharged and both counters are reset during this start up period. Conversion begins at the end of the reset pulse and ends with a pulse generated either by the clock

counter or by an overflow condition in the data counter. This pulse disables further inputs into both counters and triggers a 10  $\mu$ s shutdown cycle. During the shutdown cycle Data Valid goes low for 5  $\mu$ s. This binary sequence is shown in the timing diagrams. Busy is true high, and when the circuit is busy, Initiate conversion has no effect and may be high or low. Data Valid is also true high. The data from a conversion remain valid for as long as power is applied to the circuit or until Data Valid falls at the end of a subsequent conversion, at which time the output data are updated to reflect the latest conversion.

3 1/2 Digit ADC

Latched Outputs

w/Parallel BCD Output
10 mS Conversion Time





## Pin Functions Initiate Conversion Input

Accepts CMOS and most 5 V logic inputs. Applying a logic "1" to the Initiate Conversion pin initiates the A/D conversion cycle. Once conversion has been initiated, the cycle cannot be interrupted, and the Initiate Conversion pin is disabled until conversion is complete. Two modes of operation are permitted, clocked or free-running. For clocked operation the Initiate Conversion input is held at logic "0" for standby and taken to logic "1" when a conversion is desired. For freerunning operation the Initiate Conversion pin is connected to V<sub>DD</sub> or similar permanent logic "1" voltage.

#### **Busy Output**

A digital status output which is compatible with CMOS logic and low power TTL (can sink and source  $500 \ \mu$ A). A logic "1" output on the Busy pin indicates a conversion cycle is in process. A logic "1" to logic "0" transition indicates that conversion is complete and the result has been latched at the Digits Out pins. A logic "0" to logic "1" transition indicates a new conversion cycle has been initiated. If the device is operating in the free-running mode, the Busy output will remain low for approximately  $2.5 \ \mu$ s, marking the completion and initiation of consecutive conversion cycles.

## Data Valid Output

A digital status which is compatible with CMOS logic and low power TTL (can sink and source 50  $\mu$ A). A logic "1" output at the Data Valid pin indicates that the Digits Out pins are latched with the result of the last conversion cycle. The Data Valid output goes to logic "0" approximately 5  $\mu$ s before the completion of a conversion cycle. During this 5  $\mu$ s interval new data is being transferred to the Digits Out pins, and the Digits Out are not valid.

#### **Digits Out**

(ones, tens, hundreds and thousand)

The BCD digit outputs which are the result of the A/D conversion. These outputs are CMOS logic and low power TTL compatible.

#### 3 1/2 Digit ADC w/Parallel BCD Output • 10 mS Conversion Time

Latched Outputs

#### Applications Information Input/Output Relationships

The analog input voltage  $\left(V_{\text{IN}}\right)$  is related to the output by the transfer equation:

Digital Counts = 
$$\frac{V_{IN} \cdot A \cdot R_{REF}}{R_{IN} \cdot V_{REF}}$$
$$A = 4128$$

where Digital Counts is the value of the BCD output word presented at Digits Out pins in response to V<sub>IN</sub>.

The digital output code format is as follows:

Analog Input	Digital Output	
V <sub>IN</sub> ≤ Full-Scale	1100110011001	
= Full-Scale -1 LSB = 1 LSB ≤ 0	1100110011001 0 000 1 0 000 0	

## **External Component Selection**

Obtaining a high accuraccy conversion system depends on the voltage regulation of V<sub>REF</sub> and the thermal stability of R<sub>IN</sub> and R<sub>REF</sub>. The exact dependence is given by the transfer function. System accuracy also depends, to a lesser degree, on the voltage regulation of V<sub>DD</sub> and V<sub>SS</sub>. The supply connections V<sub>DD</sub> and V<sub>SS</sub> should have bypass capacitors of value 0.1  $\mu$ F or larger right at the device pins.

#### RIN, REF

Values of these components are chosen to give a full-scale input current of approximately 10  $\mu$ A and a reference current of approximately -20  $\mu$ A.

$$R_{IN} \cong \frac{V_{IN} \text{ Full-Scale}}{10 \ \mu \text{A}} \qquad R_{REF} \cong \frac{V_{REF}}{-20 \ \mu \text{A}}$$

Examples:

$$\mathsf{R}_{\mathsf{IN}} \cong \frac{10 \mathsf{V}}{10 \ \mu \mathsf{A}} = 1 \mathsf{M}_{\mathsf{\Omega}} \qquad \mathsf{R}_{\mathsf{REF}} \cong \frac{-6.4 \mathsf{V}}{-20 \ \mu \mathsf{A}} = 320 \mathsf{k}_{\mathsf{\Omega}}$$

Note that these values are approximations, and the exact relationships are defined by the transfer equation. In practice, the value of R<sub>IN</sub> typically would be trimmed using the optional gain adjust circuit to obtain full-scale output at V<sub>IN</sub> Full-Scale (see adjustment procedure). Metal film resistors with 1% tolerance or better are recommended for high accuracy applications because of their thermal stability and low noise generation.

#### RBIAS

Specifications for the TSC8750 are based on  $R_{BIAS} = 100 \text{ k}\Omega \pm 10\%$  unless otherwise noted. However, there are instances when the designer may want to change this resistor in order

to affect the conversion time and the supply current. By decreasing R<sub>BIAS</sub> the A/D will convert much faster and the supply current will be higher. (For example: When R<sub>BIAS</sub> is 20 k the conversion time is reduced by 1/3, and the supply current will increase from 2 mA to 7 mA.) Likewise, if the R<sub>BIAS</sub> is increased the conversion time will be longer and the supply current will be much lower. (For example: When R<sub>BIAS</sub> = 1 m $\Omega$  the conversion time will be six times longer, and the supply current is now reduced to .5 mA). For details of this relationship refer to AN-9 typical performance curves.

#### RDAMP

Exact value not critical but should have a nominal value of 100  $\Omega$  ±10%. Locate close to pin 14.

#### CDAMP

Exact value not critical but should have a nominal value of 270 pF  $\pm$ 20%. Locate close to pin 14.

#### CINT

Exact value not critical but should have a nominal value of 68 pF  $\pm$ 10%. Low leakage types are recommended, although mica or ceramic devices can be used in applications where their temperature limits are not exceeded. Locate as close as possible to pins 14, 15.

#### VREF

A negative reference voltage must be supplied. This may be obtained from a constant current source circuit or from the negative supply.

#### VDD, VSS

Power supplies of  $\pm 5$  V are recommended, with 0.05% line and load regulation and 0.1  $\mu$ F decoupling capacitors.

#### **Adjustment Procedure**

The test circuit diagram shows optional circuits for trimming the zero location and full-scale gain. Because the digital outputs remain constant outside of the normal operating range (i.e. below zero and above full-scale), it is recommended that transition points be used in setting the zero and full-scale values. Recommended procedure is as follows:

- Set the initiate conversion control high to provide free-run operation and verify that converter is operating.
- Set V<sub>IN</sub> to +1/2 LSB and trim the zero adjust circuit to obtain a 000 . . . 000 . . . to 000 . . . 001 transition. This will correctly locate the zero end.
- For full-scale adjustment, set V<sub>IN</sub> to the full-scale value less 1 1/2 LSB and trim the gain adjust circuit for a 1100110011000 to 1100110011001 transition.

If adjustments are performed in this order, there should be no interaction and they should not have to be repeated.

# TSC8750

#### 3 1/2 Digit ADC w/Parallel BCD Output • 10 mS Conversion Time • Latched Outputs

## **TSC8750**

## **Application/Design Circuits**

## 3 1/2 Digit A/D with LCD Display



## **Bipolar Operation (+ and - inputs)**



#### 3 1/2 Digit ADC w/Parallel BCD Output • 10 mS Conversion Time

Latched Outputs

**TSC8750** 

7

## Microprocessor-Based ADC System



## **Package Information**



